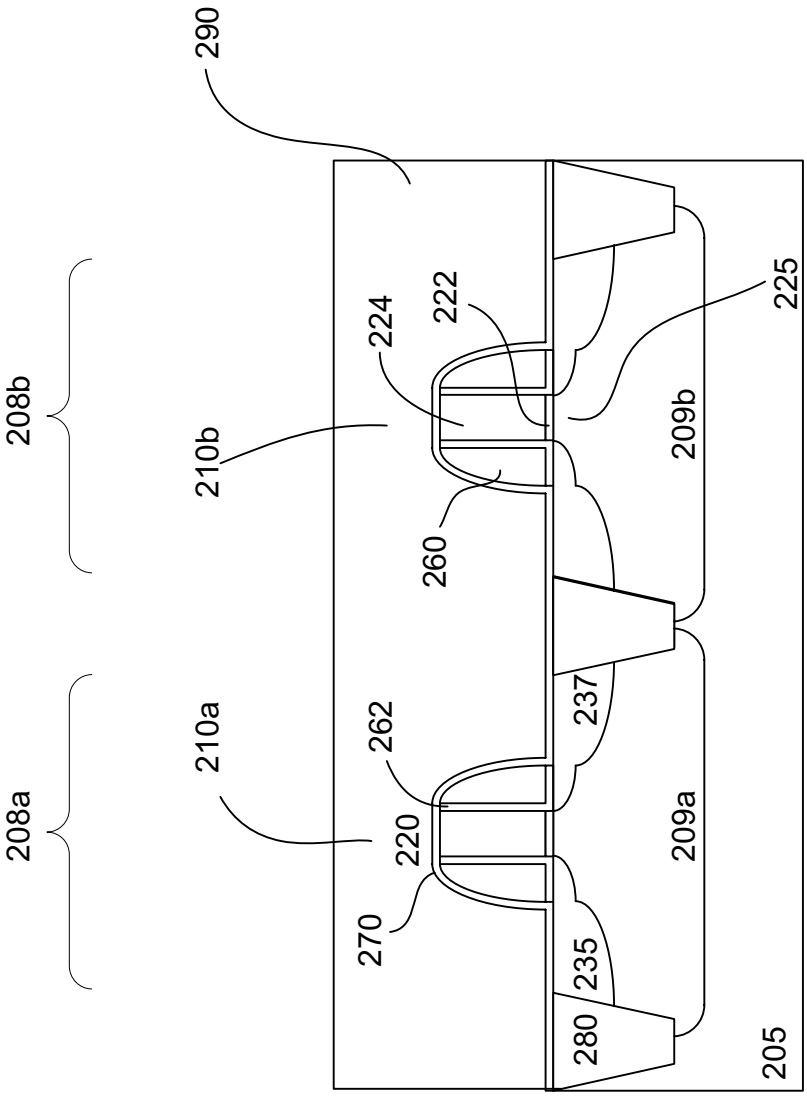
290
208b
208a
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210a
224
222
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260
262
237
220
209a
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235
280
205
200

Fig. 1

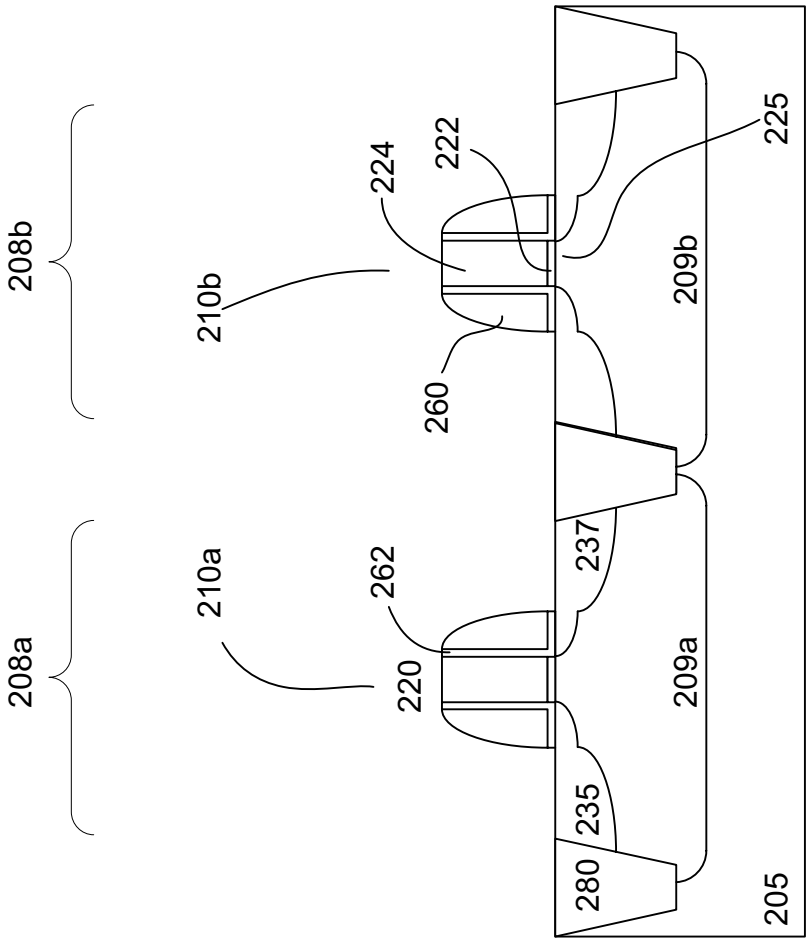
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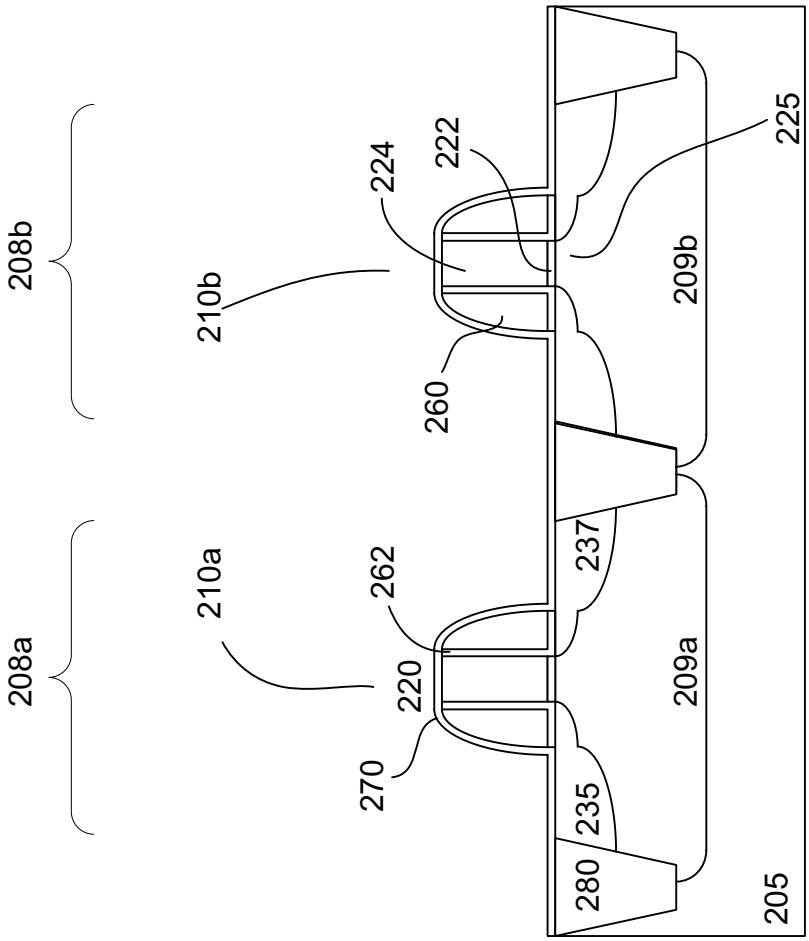
Fig. 2a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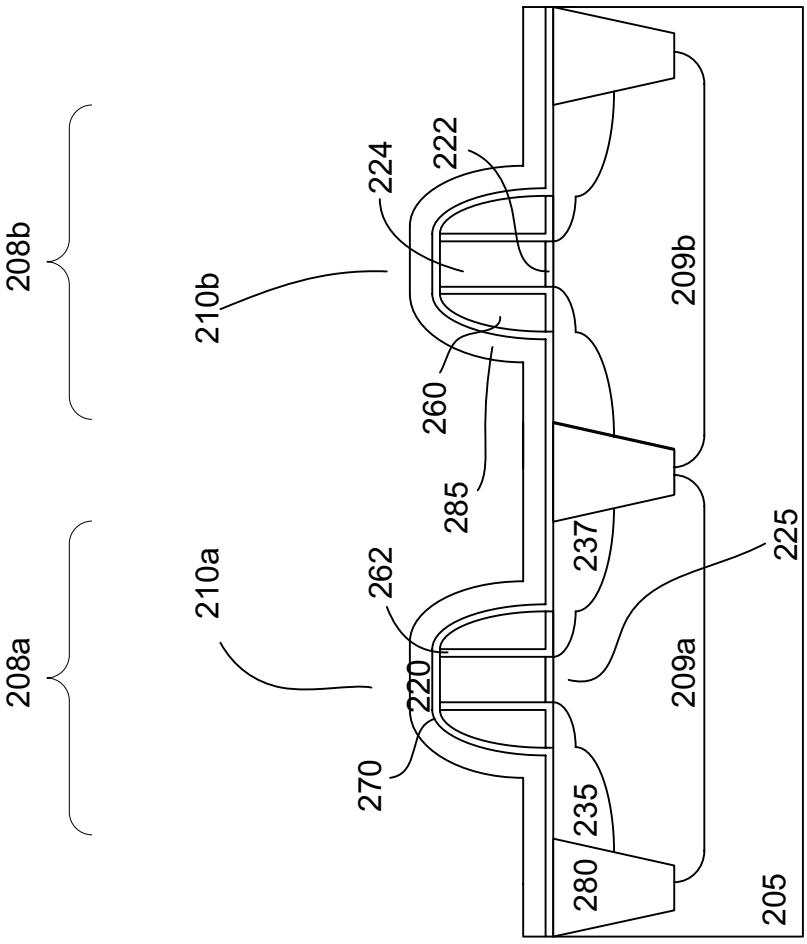
205

Fig. 2b


208b
208a
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260
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209b
209a
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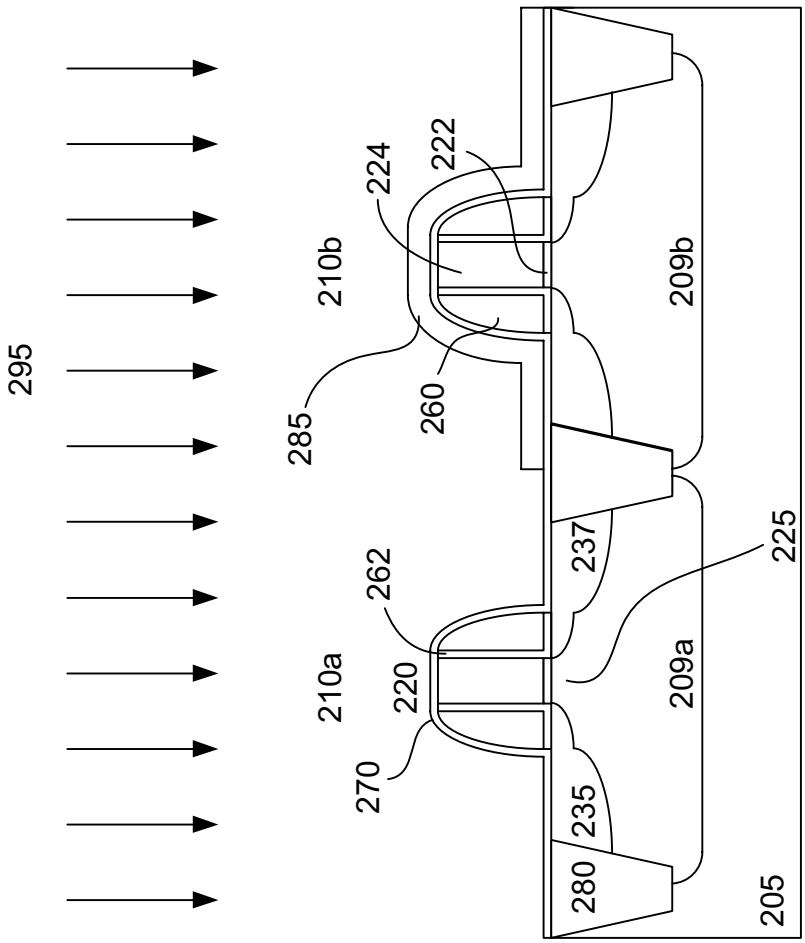
280
205

Fig. 2c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280
205

Fig. 2d

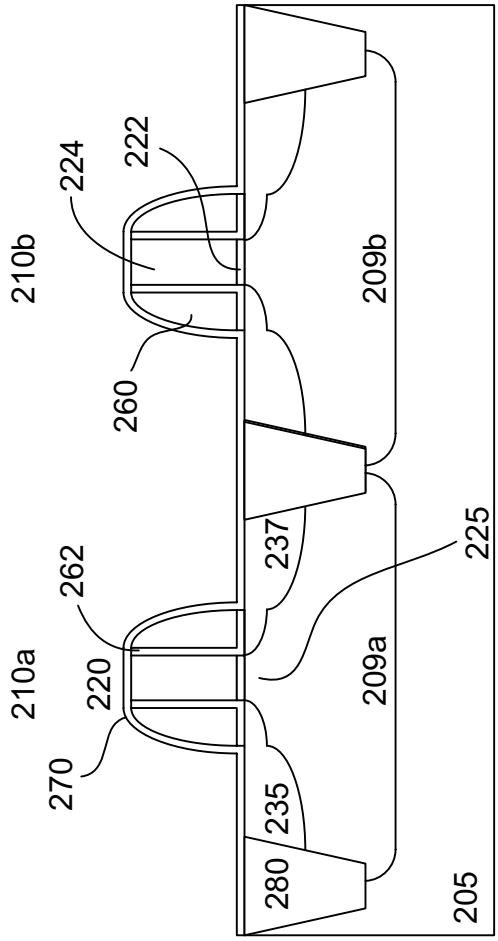
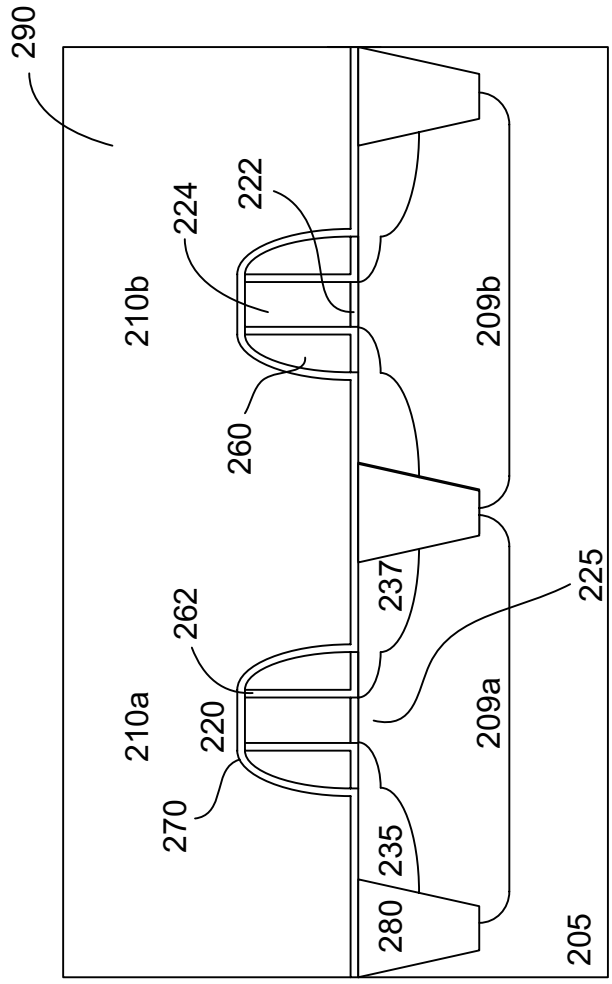


Fig. 2e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209a
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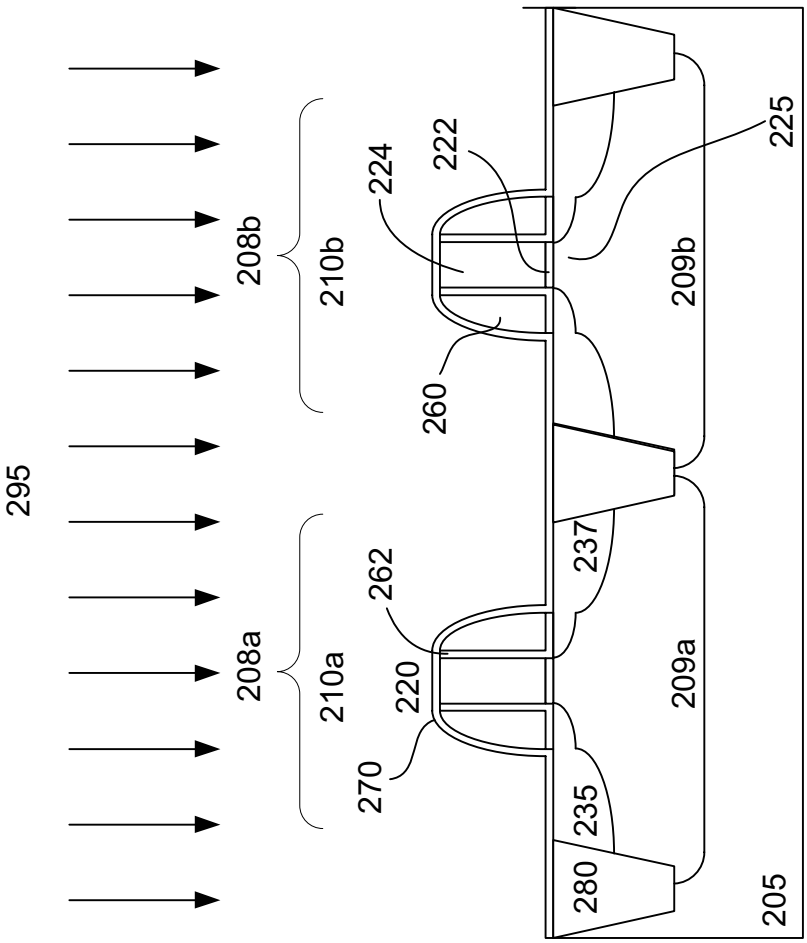
280
205

Fig. 2f


295
208b
210b
208a
210a
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260
209b
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209a
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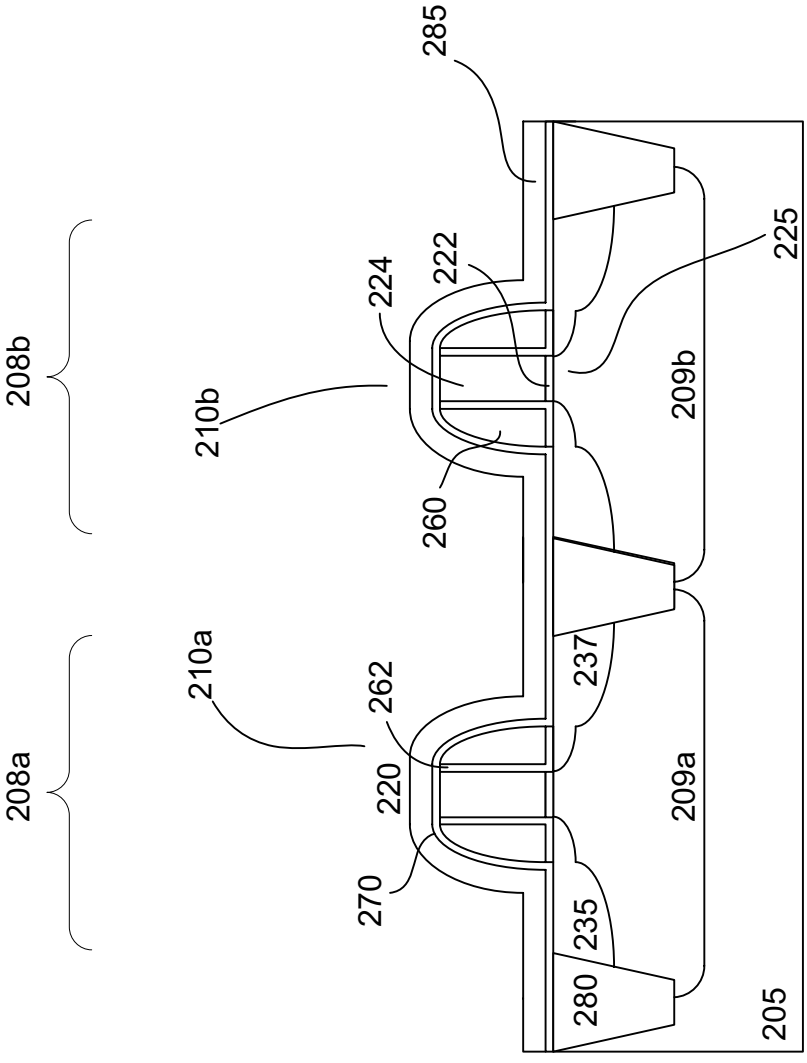
280
205

Fig. 3a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225
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208b
210b
209b
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210a
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208a
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209a
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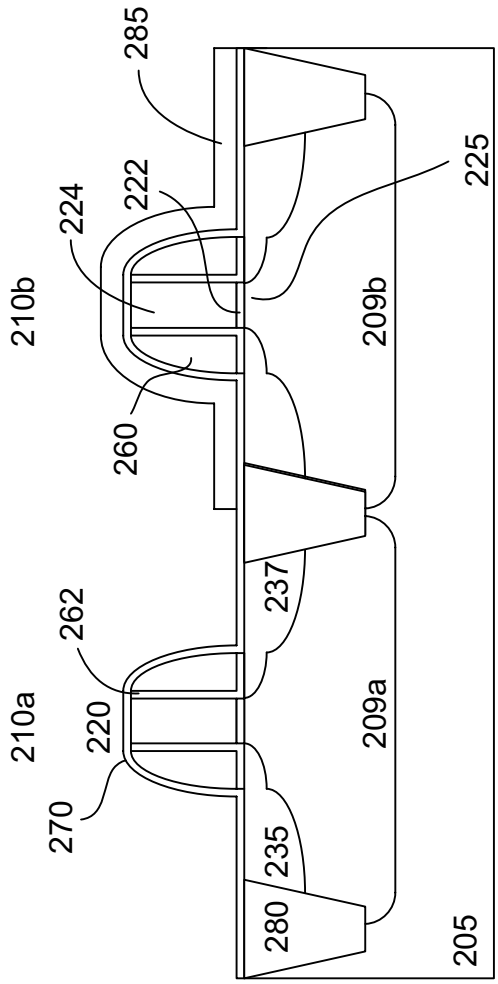
Fig. 3b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210b
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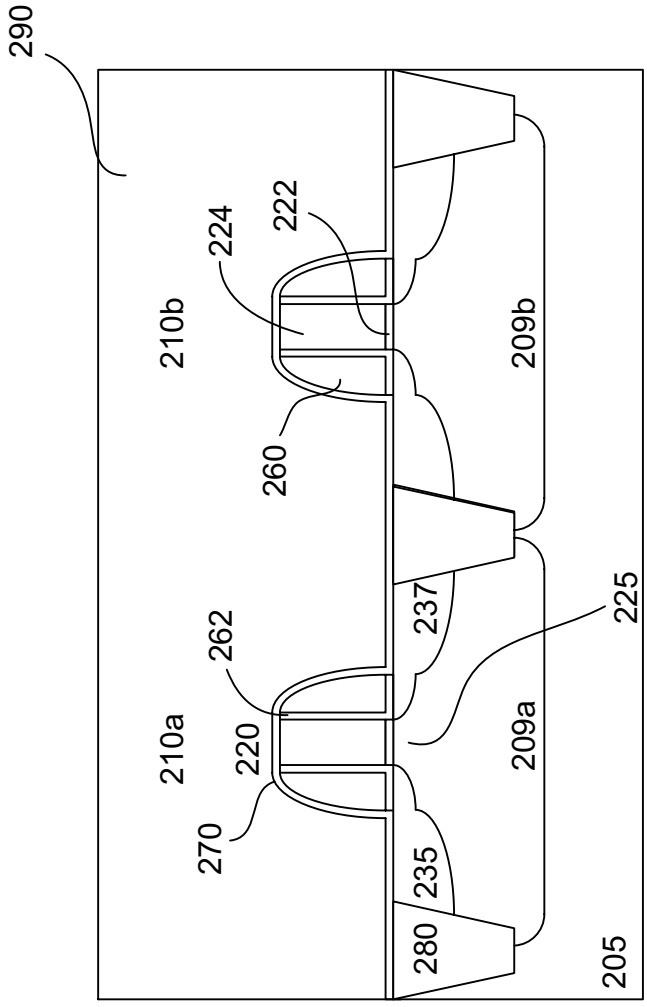
280
205

Fig. 3c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209a
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280
205

Fig. 3d

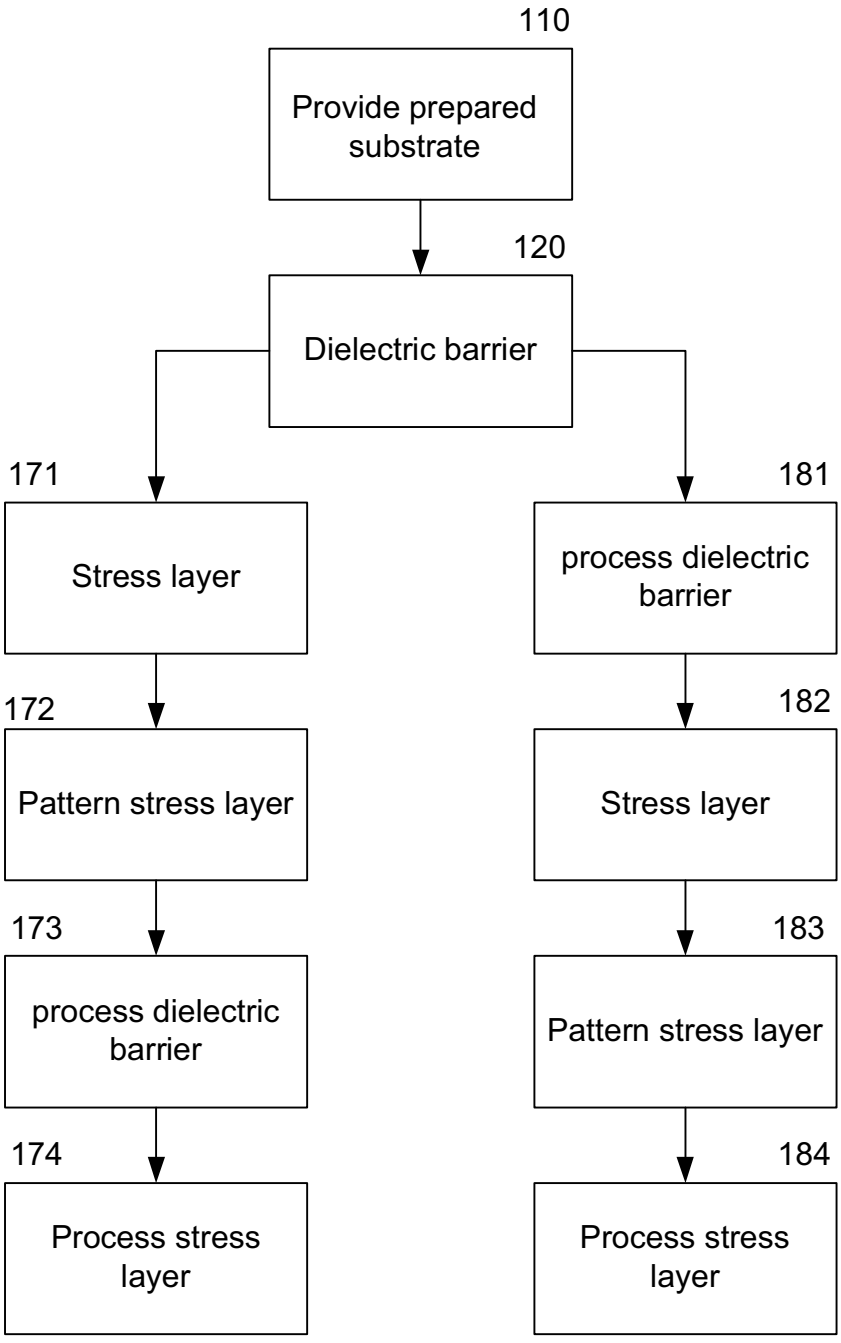
110
Provide prepared substrate
120
Dielectric barrier
171
Stress layer
172
Pattern stress layer
173
process dielectric barrier
174
Process stress layer
181
process dielectric barrier
182
Stress layer
183
Pattern stress layer
184
Process stress layer
100

Fig. 4